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Press Release

3D Glass Solutions Announces Highest Efficiency 5G IPD RF Filters

Albuquerque, New Mexico -- 3D Glass Solutions, Inc. (3DGS), a world-class expert on the fabrication of electronic packages and devices using photo-definable glass-ceramics, announced today the development and production of the highest efficiency 5G integrated passive devices (IPD) for radio frequency (RF) filters. These RF filters have been designed to operate as bandpass filters for frequencies at 5GHz and 28GHz with less than 1.0 dB of insertion loss.

“5G technology is expected to dramatically improve the performance of mobile networks and wireless systems in addition to enabling new products and applications in the Internet of Things (IoT), Augmented Reality (AR), and Virtual Reality (VR) markets”, said Jeb Flemming, Chief Executive Officer of 3DGS. “3DGS has developed low-cost solutions for these rapidly expanding RF markets. 3DGS’ technology overcomes the limitations that exist with traditional RF filters. The combination of smallest size, lowest insertion loss, and lowest power consumption provides a significant product differentiation for our customers.”

3DGS’ 5G RF filters are manufactured using APEX® Glass, a material which has significant benefits over legacy PCB materials, such as:

- up to 70% reduced chip size
- up to 50% power reduction
- up to 50% increase in wireless bandwidth
- broadband applications ranging from DC to over 100GHz

3DGS is actively looking to expand its strategic business relationships to accelerate the deployment of its high performance and high frequency RF filter technology. Our Key Industrial Partners receive prioritized product development and manufacturing support. 3DGS’ RF technology provides our customers with the ultimate in enhanced performance and reduced cost through the integration of RF IPD components (filters, antenna, and other passive devices) directly into a custom APEX® Glass-based System-in-Package (SiP).

ABOUT 3D GLASS SOLUTIONS

3DGS is a world-class expert on the fabrication of electronic packages and devices using photo-definable glass-ceramics. We produce a wide variety of OEM glass-based System-in-Package (SiP) devices using our patented APEX® Glass technology for applications such as telecommunication devices, MEMS sensors, Internet infrastructure components, integrated photonic components, and high-frequency and high-performance RF devices. We have created foundational patent positions related to all photo-sensitive glass-ceramic materials and devices. 3DGS owns the fundamental intellectual property (IP) for all four positions (materials, design, systems, & manufacturing) related to glass-ceramic devices for the electronics packaging industry. We leverage our unique product solutions providing device manufacturing and systems integration services for a number of standard and custom products. To become a Key Industrial Partner, to receive a detailed 3DGS product listing, or to request a sample 5G bandpass filter, please visit <http://www.3DGlassSolutions.com> or contact:

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